


Full Material Declaration for attached parts list

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	<p>Diotec Semiconductor AG DUNS number: 330866844 -, Kreuzmattenstr. 4, Heitersheim, 79423, Germany Declarations authorised by: Udo Steinebrunner, Product Manager, -</p>
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Declaration effective from: 02 January 2024 [Approved on 23 February 2024, 10:08 GMT]

Materials and substances

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	0.5%	Nickel REACH Article 67 Exemption	7440-02-0	0.4%
			Aluminum	7429-90-5	2.5%
			Silver	7440-22-4	28.6%
			Silicon	7440-21-3	68.5%
Encapsulation	Glass	20.36%	Aluminium oxide	1344-28-1	2%
			Sodium oxide (Na ₂ O)	1313-59-3	3%
			Lithium oxide (Li ₂ O)	12057-24-8	4%
			Rutile	1317-80-2	4%
			ZINCITE (MINERAL)	1314-13-2	4%
			Potassium oxide (K ₂ O)	12136-45-7	7.5%
			BORON TRIOXIDE	1303-86-2	20%
			Silicon Dioxide	7631-86-9	55.5%
Inner preparation	Copper alloys	9.39%	Copper	7440-50-8	24%
			Iron	7439-89-6	34%
			Nickel REACH Article 67 Exemption	7440-02-0	42%
Leadfinish	Tin plating	0.09%	Tin	7440-31-5	100%
Leadframe	Copper alloys	69.66%	Iron	7439-89-6	18%
			Copper	7440-50-8	82%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
DO-35/SOD-27_Pb-free	Diode Axial	0.09157	g
